

# Chip NTC Thermistors (Protection Device)

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## NTCG163JX103DT1S



**Applications** Automotive Grade

**Features**  
150°C 150°C  
AEC-Q200 AEC-Q200

**Series** NTCG

**Status** Production

**Brand** TDK

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 Images are for reference only and show exemplary products.

Size	
Length(L)	1.60mm ±0.10mm
Width(W)	0.80mm ±0.10mm
Thickness(T)	0.80mm ±0.10mm
Terminal Width(B)	0.20mm Min.
Recommended Land Pattern (PA)	0.70mm ±0.10mm
Recommended Land Pattern (PB)	0.70mm ±0.10mm
Recommended Land Pattern (PC)	0.70mm ±0.10mm

Electrical Characteristics	
Resistance [at 25°C]	10kΩ
Resistance Tolerance	±0.5%
B value (Typ.) [25/50°C]	3380K
B value (Typ.) [25/85°C]	3435K
B value (Typ.) [25/100°C]	3453K
B value Tolerance	±0.7%
Max. Electric Power [at 25°C] <span>?</span>	125mW
Permissible Operating Current [at 25°C] <span>?</span>	310μA
Thermal Dissipation Constant [at 25°C] <span>?</span>	1mW/°C   1mW/K

Other	
Max. Operating Temperature	150°C
Soldering Method	Reflow
UL File No.	
AEC-Q200	Yes
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	4000pcs
Weight	0.005g



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